

1 Product profile

1.1 General description

Two planar PIN diodes in common cathode configuration in a SOT23 small plastic SMD package.

1.2 Features and benefits

- Two elements in common cathode configuration in a small-sized plastic SMD package
- · Low diode capacitance
- · Low diode forward resistance

1.3 Applications

General RF application

2 Pinning information

Table 1. Discrete pinning

Pin	Description	Simplified outline	Graphic symbol
1	anode		_
2	anode	3	3
3	common cathode	1 2 Top view	1 2 aaa-029921



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3 Ordering information

Table 2. Ordering information

Type number	Package	:kage					
	Name	Description	Version				
BAP50-05	-	plastic surface-mounted package; 3 leads	SOT023				

4 Marking

Table 3. Marking code

Type number	Marking code
BAP50-05	1C%

5 Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	continuous reverse voltage		-	50	V
lF	continuous forward current		-	50	mA
P _{tot}	total power dissipation	T _{sp} ≤ 90 °C	-	250	mW
T _{stg}	storage temperature		-65	+150	°C
T _j	junction temperature		-65	+150	°C

6 Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Тур	Unit
11(J-3P)	thermal resistance from junction to solder point		220	K/W

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7 Characteristics

Table 6. Characteristics

 T_i = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V _F	forward voltage	I _F = 50 mA		-	0.95	1.1	V
V_R	reverse voltage	I _R = 10 μA		50	-	-	V
I _R	reverse current	V _R = 50 V		-	-	100	nA
C _d	diode capacitance	f = 1 MHz (see Figure 1)			·	·	<u>'</u>
		V _R = 0 V		-	0.45	-	pF
		V _R = 1 V		-	0.35	0.6	pF
		V _R = 5 V		-	0.3	0.5	pF
r _D	diode forward resistance	f = 100 MHz (see Figure 2)					
		I _F = 0.5 mA	[1]	-	25	40	Ω
		I _F = 1 mA	[1]	-	14	25	Ω
		I _F = 10 mA	[1]	-	3	5	Ω

^[1] Guaranteed on AQL basis: inspection level S4, AQL 1.0.

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8 Graphical data

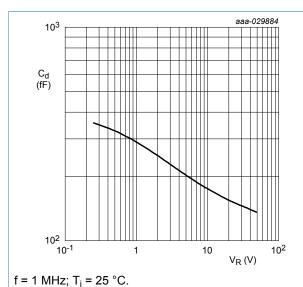
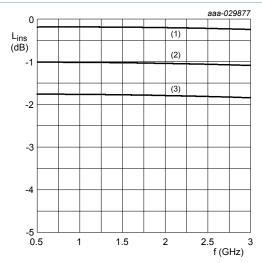


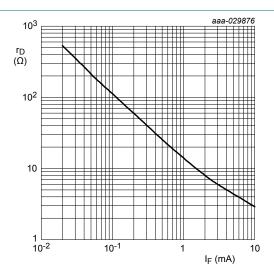
Figure 1. Diode capacitance as a function of reverse voltage (typical values)



Diode inserted in series with a 50 Ω strip line circuit and biased via the analyzer T-network. T_{amb} = 25 $^{\circ}C.$

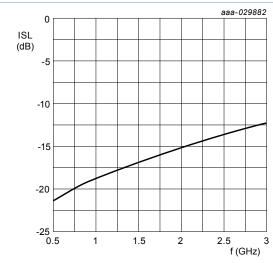
- (1) $I_F = 10 \text{ mA}$
- (2) $I_F = 1 \text{ mA}$
- (3) $I_F = 0.5 \text{ mA}$

Figure 3. Insertion loss of the diode as a function of frequency (typical values)



f = 100 MHz; $T_i = 25 ^{\circ}\text{C}$.

Figure 2. Diode forward resistance as a function of forward current (typical values)

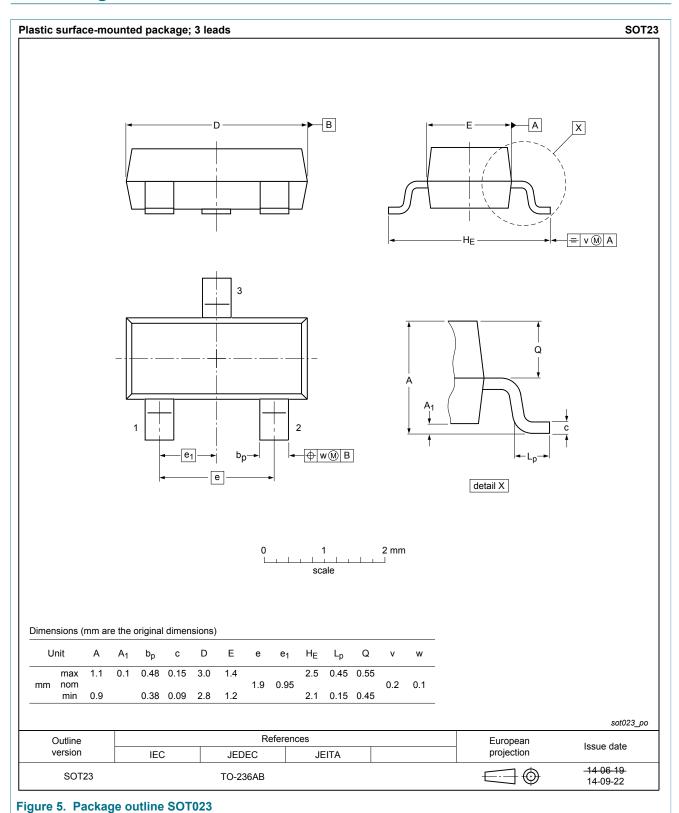


Diode zero biased and inserted in series with a 50 Ω strip line circuit. T_{amb} = 25 $^{\circ}C.$

Figure 4. Isolation of the diode as a function of frequency (typical values)

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9 Package outline



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10 Abbreviations

Table 7. Abbreviations

Acronym	Description
AQL	acceptable quality level
PIN	P-type, intrinsic, N-type
RF	radio frequency
S4	special inspection level 4
SMD	surface-mounted device

11 Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP50-05 v.3.1	20190208	Product data sheet	-	BAP50-05 v.3
Modifications: • aligned the title of the data sheet with the description on the Internet				
BAP50-05 v.3	20181126	Product data sheet	-	BAP50-05 v.2.1
Modifications:	• Section 1.2 "Features and benefits" has been updated. • The "Legal information" pages have been updated.			
BAP50-05 v .2.1	19990510	Product data sheet	-	BAP50-05 v.1

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12 Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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